© Copy	rial Compositio right 2005. IPC, Bar ional and Pan-Amer	nnockburn, Illin	ois. All rights reserved	under both	This docume level parts, th	ent is a declara he declaration	ation of the	e substances sses all lowe	within the n r level mater	nanufacture rials for wh	er listed ite hich the ma	em. Note: unufacture	if the item is an as er has engineering	ssembly with lowe responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Ty http://www.ipc.org/IPC-175x Distribu				e *	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
Supplier Information						·									
Company name*			Company unique ID			Unique ID Authority					Response Date*				
onsemi												2023-06-08			
Contact Name			Title - Contact			Phone - Contact*					Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards	Produc	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com						
Requester Item Nur	Requester Item Number Mfr Item Number FUSB302B10M		tem Number Mfr Item Name			Effective Da	te Versi	on	Manufacturing Site		W	veight*	UOM	Unit Type	
			USB-C Port Control w/ PD			2023-06-08 TH2			17.833		mg	Each			
Manufacturing Proccess	s Information		L			1								I	
Terminal Plating / G	Cerminal Plating / Grid Array Material		Ferminal Base Alloy J-S		D-020 MSL Rating		Peak Process Body Temperatur		are Max Time at Peak Temper		Temperatu	re Num	ber of Reflow Cyc	cles	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		no CU Alloy	CU Alloy 1			260		C	30		second	s 3			
Comments															
evel 1 - maximum time at pea	k temperature dur	ing soldering is	10-30 seconds												
or more information regardi	ing material compo	sition please re	fer to page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.438	mg	Supplier	Silicon (Si)	7440-21-3		0.438	mg
Die Attach	0.06	mg	Supplier	Isobornyl Methacrylate	7534-94-3		0.0036	mg
			Supplier	Silver (Ag)	7440-22-4		0.0489	mg
			Supplier	Isobornyl Acrylate	5888-33-5		0.0036	mg
			Supplier	Misc.	Proprietary Data		0.0003	mg
			Supplier	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2		0.0036	mg
Lead Frame	14.092	mg	Supplier	Zinc (Zn)	7440-66-6		0.017	mg
			Supplier	Iron (Fe)	7439-89-6		0.331	mg
			Supplier	Copper (Cu)	7440-50-8		13.74	mg
			Supplier	Phosphorus (P)	7723-14-0		0.004	mg
Mold Compound-Black	2.743	mg	Supplier	Carbon Black (C)	1333-86-4		0.0137	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		2.4138	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.1783	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.1372	mg
Plating	0.103	mg	Supplier	Palladium (Pd)	7440-05-3		0.009	mg
			В	Nickel (Ni)	7440-02-0		0.092	mg
			Supplier	Gold (Au)	7440-57-5		0.002	mg
Wire Bond - Au	0.397	mg	Supplier	Gold (Au)	7440-57-5		0.397	mg